HZ0603A222R-10
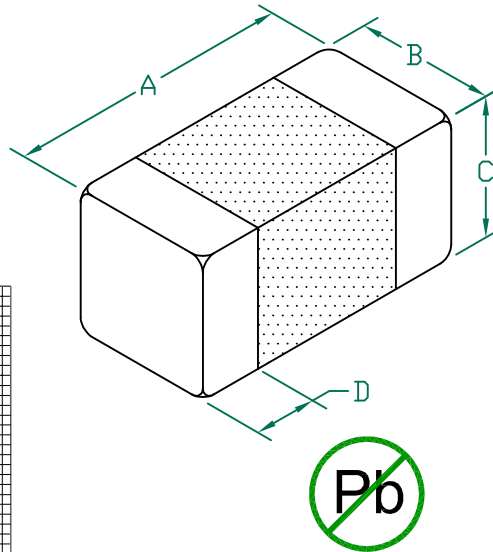
PHYSICAL DIMENSIONS:

A 1.60 [.063]   ± 0.15 [.006]
B 0.80 [.031]   ± 0.15 [.006]
C 0.80 [.031]   ± 0.15 [.006]
D 0.36 [.014]   ± 0.15 [.006]
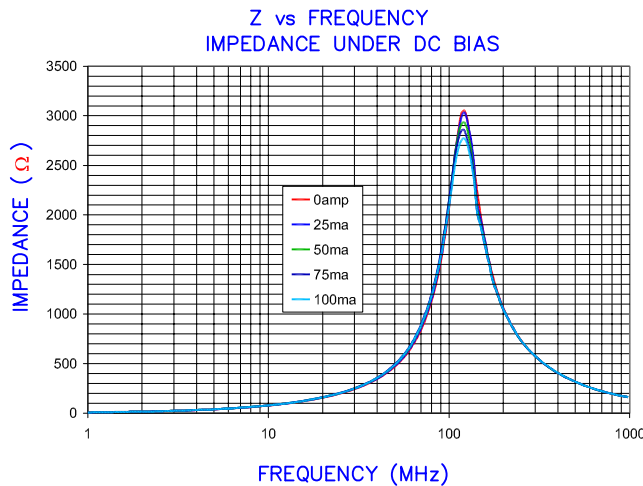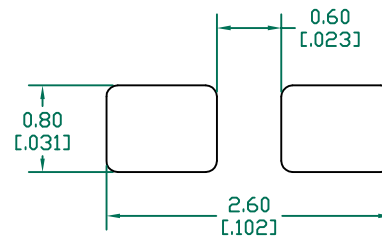
ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)		DCR (Ω)	Rated Current
Nominal	2200		
Minimum	1650		
Maximum	2750	1.5	100 mA

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL.

2. TERMINATION FINISH IS 100% TIN.

3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.

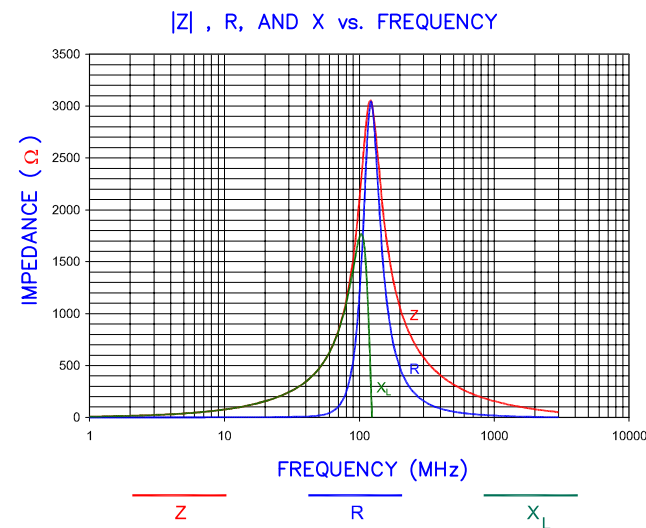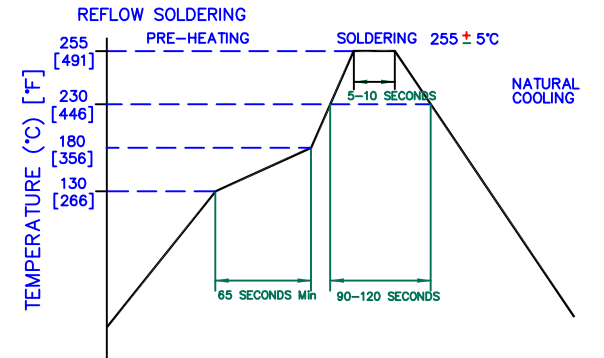4. OPERATEING TEMPERATURE TEMP: −40°C~+125°C (INCLUDING SELF−HEATING)

Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS

Legend: 0amp, 25ma, 50ma, 75ma, 100ma

FREQUENCY (MHz)

|Z| , R, AND X vs. FREQUENCY

FREQUENCY (MHz)

Z   R X_L

AGILENT E4991A RF Impedance/Material Analyzer
HP 16194A Test Fixture. TEST REF. 3228

LAND PATTERNS FOR REFLOW SOLDERING

0.60 [.023]
0.80 [.031]
2.60 [.102]

(For wave soldering, add 0.762 [.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS

REFLOW SOLDERING
PRE−HEATING   SOLDERING 255 ± 5°C
NATURAL COOLING
5−10 SECONDS
65 SECONDS Min   90−120 SECONDS

255 [491], 230 [446], 180 [356], 130 [266]
TEMPERATURE (°C) [°F]

RoHS 2002/95/EC

DIMENSIONS ARE IN mm [INCHES].

Laird™

REV	DESCRIPTION	DATE	INT
C	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU
B	UPDATE COMPANY LOGO ADD ROHS	02/22/08	JRK
A	ORIGINAL DRAFT	04/03/04	TMB

PROJECT/PART NUMBER: HZ0603A222R-10
REV: C
PART TYPE: CO−FIRE
DRAWN BY: TMB
DATE: 04/03/04
SCALE: −
CAD #: HZ0603A222R−10−C
TOOL #: −
SHEET: 2 of 2